General Description

The MAX20342 is a USB Type- C^{\circledR} charger detector that is also capable of detecting chargers compliant with the USB Battery Charging Specification Revision 1.2. The USB Type-C charger detection circuitry functions as a UFP or DRP depending on factory configuration.

The device implements USB Type-C detection logic and enables systems to support charging based on USB Type-C ports. The device also includes charger detection capability for BC1.2 compatible chargers and detects USB standard downstream ports (SDPs), USB charging downstream ports (CDPs), dedicated charger ports (DCPs), and other proprietary chargers. GPIO outputs allow the MAX20342 to control an external lithium-ion (Li+) battery charger based on charger detection results.

The MAX20342 integrates a resistance detection block that can be used to automatically configure factory configuration states based upon attached resistors. Additionally, the resistance measurement can be configured to detect the presence of moisture in the USB Type-C connector.

The MAX20342 also features an integrated low onresistance, low-capacitance double-pole double-throw (DPDT) USB switch that can pass Hi-Speed USB, fullspeed USB, low-speed USB, and UART signals. The switch position can be automatically configured by the USB detection logic or manually controlled.

The MAX20342 features high-ESD protection up to ±15kV human-body model (HBM) on CC1, CC2, SBU1, and SBU2 pins. The CDP and CDN pins are protected against ESD up to ±6kV. The MAX20342 is specified for ±15kV Air-Gap and ±8kV Contact Discharge IEC 61000-4-2 on the CC1, CC2, SBU1, and SBU2 pins. The MAX20342 is available in a 24-bump, 0.4mm pitch, 2.62mm x 2.02mm wafer-level package (WLP) and operates over the -40ºC to +85ºC extended temperature range.

Applications

- DSCs and Camcorders
- **Tablets**
- **Smartphones**
- e-Readers

USB Type-C® is a registered trademark of USB Implementers Forum.

Apple is a registered trademark of Apple Inc.

Samsung is a registered trademark of Samsung Electronics Co., Ltd

19-100858; Rev 3; 9/21

MAX20342 USB Type-C Charger Detector with Integrated OVP

Benefits and Features

- Low Power Consumption
	- Battery Standby Current 17μA (typ)
	- Battery Shutdown Current 2.5μA (typ)
- Delivers USB Compliance and Flexibility
- Compliant with USB Type-C Specification Revision 1.3
- Supports USB Battery Charger Specification Revision 1.2
- Detects Proprietary Chargers such as Apple[®] and Samsung®
- Simplifies Complex System Designs
	- Integrated Overvoltage Protection
	- Negative Swing Audio Capable Hi-Speed USB/UART Switches
	- Automatic Switch and Charger Interface Control
	- Full Control through I2C Interface
	- Interrupts for Device Status Changes
- Improves Quality and Reliability
	- Automatic Factory Mode Configuration
	- USB Type-C Port Moisture Detection
	- Low-Corrosion DRP Mode
- Robust Protection
	- V_B Connection Withstands up to $+30V$
	- V_B Surge Protection up to $±120V$
	- ±15kV HBM ESD Protection on CC1, CC2, SBU1 and SBU2 Pins
	- ±6kV HBM ESD Protection on CDP and CDN Pins
	- \cdot \pm 15kV Air-Gap IEC 61000-4-2 on CC1, CC2, SBU1, and SBU2 Pins
	- ±8kV Contact Discharge IEC 61000-4-2 on CC1, CC2, SBU1, and SBU2 Pins
- Saves Board Space
	- 2.62mm x 2.02mm WLP Package

[Ordering Information](#page-91-0) appears at end of data sheet.

Simplified Block Diagram

Absolute Maximum Ratings

Note 1: CC1 and CC2 pins can withstand a short to +20V with a series 10kΩ resistor (sinking 2mA). Continuous Current is guaranteed for 100,000 hours at $T_A = 120^{\circ}$ C. Throughout the data sheet, Current refers to the aforementioned condition of Continuous Current.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or
any other conditions beyond those in *device reliability.*

Package Information

24-WLP

For the latest package outline information and land patterns (footprints), go to *[www.maximintegrated.com/packages](https://www.maximintegrated.com/en/design/packaging.html)*. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to *[www.maximintegrated.com/thermal](https://www.maximintegrated.com/en/design/technical-documents/tutorials/4/4083.html)[tutorial](https://www.maximintegrated.com/en/design/technical-documents/tutorials/4/4083.html)*.

Electrical Characteristics

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

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(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

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(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

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(V_{BAT} = 3.6V , V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

(V_{BAT} = 3.6V, V_B = 5V, C_{VDD} = 1µF, C_{VB} = 1µF, C_{OUT} = 1µF, C_{BAT} = 1µF, limits are production tested at T_A = +25°C. Limits over the operature range and relevant supply voltage range are guaranteed by design and characterization.

the operating temperature range and relevant supply voltage range are quaranteed by design and characterization.						
PARAMETER	SYMBOL	CONDITIONS	MIN	TVO	MAX	UNITS
		CC1/CC2, SBU1/SBU2	±45			

Note 2: During moisture detection in manual configuration, if more than one pin among SBU1, SBU2, CDP, CDN, CC1, and CC2 is pulled up at the same time, the pullup current is forced on a common internal node shared by the forcing switches, while the voltage measured by the ADC is that of another common internal node shared by the sensing switches. Both forcing and sensing switches have an R_{MOIST_SWPU} resistance. For example, if just two pins are pulled up, an overall equivalent resistance equal to RMOIST_SWPU is applied between them. If the pullup pins are more than two, the resistive mesh internally applied between the pins is that shown in *[Figure 7](#page-30-0)*, where the SWP[n] switches are the forcing/sensing ones with RMOIST_SWPU resistance.

Typical Operating Characteristics

 $(T_A = +25\degree C, V_B = 5V,$ unless otherwise noted.)

 $(T_A = +25\degree C, V_B = 5V,$ unless otherwise noted.)

Bump Configuration

Pin Descriptions

Functional Diagram

Detailed Description

USB BC1.2 Charger Detection

The MAX20342 USB charger detection block supports USB BC1.2 with the additional capability to automatically detect some common proprietary charger types. Note that after the secondary detection of USB BC1.2 finishes, the device does not keep V_{DP} s_{RC} enabled if DCP is detected. While this behavior can cause the device to fail the DCP test in USB BC1.2 compliance, this is not expected to cause any issue in the detection of BC1.2 chargers.

The Charger Detection State Machine follows USB BC1.2 requirements and detects SDP, CDP, and DCP charger types (see $_{\text{Table 1}}$ $_{\text{Table 1}}$ $_{\text{Table 1}}$) In addition to the USB BC1.2 State Machine, the MAX20342 also detects a limited number of proprietary charger types (Apple, Samsung, and generic 500mA). The MAX20342 always reports SDP/CDP/DCP in addition to a detected proprietary type. For example, the Samsung proprietary charger uses D+/D- short and bias on D+/D-. The bias voltage is chosen so that, with a USB BC1.2 compliant state machine, it is detected as a DCP. The device reports this charger detected as both a DCP and a Samsung charger. See $_{Table 2}$ $_{Table 2}$ $_{Table 2}$ and $_{Table 3}$ $_{Table 3}$ $_{Table 3}$ for more details.

The MAX20342 also reports the operation status of the Charger Detection State Machine in the ChgTypRun interrupt bit in the register map.

Table 1. USB BC1.2 Charger Type Detection

Note: Charge Detect running state is indicated until the Charger Detection State Machine is complete.

Table 2. Proprietary Detection Table

Examples of ChgTyp[1:0] and PrChgTyp[2:0] values found for common chargers on the market are listed in *[Table 3](#page-20-0)*. When the MAX20342 detects the charger, it sets the CE output based on the charger type found. *[Table 4](#page-21-0)* shows D+/Dtermination for Apple chargers, Samsung charger, dedicated charger, and a standard USB host charging downstream port.

Figure 1. Apple Chargers, Samsung Charger, Dedicated Charger, and Standard USB Host Charging Downstream Port

Autoconfiguration Mode

The MAX20342 is capable of automatically setting the position of the internal analog switches, and \overline{CE} and \overline{DB} outputs based on the state of V_B voltage, CC resistor value, and SBU resistor value. See *[Table 4](#page-21-0)* for more details.

The autoconfiguration state machine starts when either the device is in Debug Accessory Sink Mode and FactAuto = 1, or the device is connected to the valid V_B voltage and USBAuto = 1. If FactAuto = 0 and USBAuto = 0, the autoconfiguration cannot start.

Table 4. Autoconfiguration Mode Table

()* \overline{CE} setting depends on NotUSBCmpl bit.

*(**)* If a USB device is detected, the OVP switch must be manually set as described in the [OVP Manual Setting](#page-22-0) section.

OVP Manual Setting

In the case where a USB device is detected and the MAX20342 needs to source power from OUT to V_{B} , and then to the USB Type-C receptacle, the OVP switch needs to be manually set. When the MAX20342 has detected through the USB Type-C that a USB device has been attached, the user must follow the procedure to source power from OUT to V_B.

- 1. Manually close the OVP switch setting (VBOVPEn = 0x3). At this point, no power source must be attached to OUT.
- 2. Wait for SwtClosedInt interrupt request. At this point the OVP switch is closed and power can be attached to OUT.
- 3. Enable power source on OUT.

The user must follow the procedure to stop power sourcing to V_{B} .

- 1. Disable power source on OUT.
- 2. Manually open the OVP switch setting (VBOVPEn = 0x0). Wait for SwtClosedInt interrupt request. At this point the OVP switch is actually open.

The power source on OUT must not exceed 2A and 5.5V to avoid triggering the OVLO threshold. This restriction avoids a voltage drop between OUT and V_B (OUT – V_B = R_{ON} x I_{MAX}) that is greater than the diode forward voltage (0.3V), which prevents current flow through the diode.

USB Type-C Detection

The MAX20342 is a complete solution for USB Type-C port charger detection and multiplexing USB and UART on a single USB Type-C connector.

The USB Type-C block detects connected accessories by using USB Type-C and USB BC1.2 charger detection. The USB Type-C block can also measure resistances on the SBU pin and automatically set switch positions and output status signals accordingly. In addition, the USB Type-C block can auto-configure switches for common connected accessories including USB cables (SDP/CDP, etc.) and customer-specific factory cables. A moisture/corrosion detection block allows the system to detect the presence of moisture in the USB Type-C port and alert the user to take specific action.

Dead Battery

In the case of a dead battery and no V_B attached, 1V voltage clamps are attached to CC1 and CC2 to ensure charging can start from a USB Type-C adapter.

CC Description

The MAX20342 can be configured to function as an Upstream Facing Port (UFP) or Dual Role Port (DRP) compliant with the USB Type-C 1.3 specification. The USB Type-C functions are controlled by a logic state machine which follows the USB Type-C standard requirements. When configured as a DRP, there is support for the optional Try.SNK function, placing priority on the Sink role.

Try.SNK Support

The MAX20342 operates as a UFP by default but can be configured to operate as a DRP. A DRP can act as either a Power Sink or a Power Source. The USB Type-C logic state machine cycles between Source and Sink at a rate of 75ms (typ). When the MAX20342 is connected to another device which is also a DRP, the source and sink roles are randomly assigned. The MAX20342 includes support for the Try.SNK state that allows the MAX20342 to be set to strongly prefer the sink role when connected to a standard DRP. If two devices with Try.SNK enable are connected, the role setting is again random.

Analog Audio Accessory Detection

The MAX20342 provides detection support for USB Type-C analog audio adapter detection by notifying the system microprocessor with an interrupt when an analog audio adapter is detected on the CC1 and CC2 pins. When an audio adapter is detected, the system is required to properly connect the audio codec to the CDP/CDN and SBU1/SBU2 with an external analog switch.

Moisture Detection

The MAX20342 supports resistance measurement between selected pins on the USB Type-C connector. This measurement can be used to determine if there is moisture or some other form of conductive debris present in the connector. The moisture detection function can be automatically configured (MoistDetAutoCfg = 1) or manually configured (MoistDetAutoCfg = 0) and also supports manual triggering (MoistDetManEn = 1) or periodic triggering (MoistDetPerEn $=$ 1). The moisture detection function is run only when the MAX20342 is not in shutdown mode and V_B or a CC connection has not been detected.

Moisture Detection Threshold RMOIST

The R_{MOIST} is defined by the combination of the ADC voltage threshold RMoistDetVth[7:0] and the selected pullup current RMoistDetIpu[1:0]. When the measured resistance is below R_{MOIST}, the ResMoistInt interrupt is asserted. Since both the voltage and current are needed to calculate resistance, the IpuResult[1:0] and ADCResultAvg[7:0] results are evaluated together to determine if moisture is detected (measured resistance < R_{MOIST}). [Table 5](#page-23-0) lists the conditions for the indication of moisture. The resistance of the moisture threshold must be set with respect to the resistance constraints listed in *[Table 7](#page-33-0)* and *[Table 8.](#page-33-1)*

Table 5. Moisture Detection Result

Automatic Configuration

If the automatic configuration mode is selected (MoistDetAutoCfg = 1), all the pulldown and pullup switches described in the *[Resistive Measurement](#page-29-0)* section are automatically controlled during moisture detection. When an automatically configured moisture detection is triggered either manually (MoistDetManEn = 1) or periodically (MoistDetPerEn = 1), the resistance is measured between one of the CC pins and ground while all other USB Type-C pins (V_B, CDP, CDN, SBU1, SBU2, and the other CC) are grounded.

If the result is Open or Abort, the moisture detection ends, no interrupt is triggered, and the result is reported in IpuResult[1:0] and ADCResultAvg[7:0]. If the result is a finite resistance above the moisture threshold defined by RMoistDetVth[7:0] and RMoistDetIpu[1:0], the detection ends, ResFiniteInt interrupt is asserted, and the result is reported. If the result is below the moisture threshold, ResMoistInt interrupt is asserted and a burst of consecutive resistive measurements is performed on CC1/CC2/SBU1/SBU2 (pulled up one at a time) to ground while the other USB Type-C pins are grounded. Finally, the burst measurement results are reported in the registers MoistDetAutoCC1/CC2Result1, MoistDetAutoCC1/CC2Result2, MoistDetAutoSBU1/SBU2Result1, and MoistDetAutoSBU1/SBU2Result2. *[Figure 2](#page-24-0)* shows the detection flow for automatically configured moisture detection.

Automatically configured moisture detection always starts on the alternate CC pin when the next detection is triggered either periodically or manually as shown in *[Figure 4](#page-26-0)*.

Figure 2. Automatically Configured Moisture Detection Flow

Manual Configuration

If manual configuration mode is selected (MoistDetAutoCfg = 0), all the pulldown and pullup switches described in the *[Resistive Measurement](#page-29-0)* section are configured manually by MoistDetPUConfig[5:0] and MoistDetPDConfig[6:0]. The two pullup and one pulldown switches associated with each USB Type-C pin can be independently configured. This mode allows measuring resistance between the USB Type-C pins in different user-defined configurations. This manually configured moisture detection can also be triggered either manually (MoistDetManEn = 1) or periodically (MoistDetPerEn = 1).

If the result of the measurement is an Abort or Open, the corresponding ResAbortInt or ResOpenInt interrupt is asserted. If the resistance result is higher than or equal to the moisture resistance threshold, ResFiniteInt interrupt is asserted. If the result (including Ground) is lower than the moisture resistance threshold, the ResMoistInt interrupt is asserted instead.

Figure 3. Manually Configured Moisture Detection Flow

Periodic and Manual Trigger

Moisture detection, either automatically or manually configured, can be triggered either manually or periodically. Moisture detection is manually triggered when MoistDetManEn is set to 1; it starts a single moisture detection. MoistDetManEn bit stays high until the end of the measurement and is then self-cleared. If MoistDetManEn is set to 1 while VB or a CC connection is detected, a moisture detection starts as soon as the cable is detached. It is also possible to cancel the pending manual triggered detection by writing a 0 to MoistDetManEn while VB or a CC connection has been detected.

When periodic triggering is enabled by setting MoisetDetPerEn to 1, the moisture detection is run periodically every 10 seconds (typ). It is also possible to manually trigger a moisture detection while periodic trigger is enabled. The 10-second timer does not reset by the manual trigger as shown in *[Figure 4](#page-26-0)* and *[Figure 5](#page-26-1)*.

Figure 4. Moisture Detection Triggering for Automatic Configuration

Figure 5. Moisture Detection Triggering for Manual Configuration

Debug Accessory Modes

The MAX20342 can automatically detect up to five accessory modes based on the measured resistance between SBU1 (or SBU2) and ground. These five resistance thresholds are selected by the corresponding RAcc1-5DetVMax[7:0], RAcc1-5DetVMin[7:0], and RAcc1-5DetIpu[1:0] register bits.

If any one of the RaccDet1-5 ranges is detected, the corresponding ResAcc1-5Int interrupt is asserted. In addition, RaccDet1-3 values also define the UART and factory modes. If one of the RaccDet1-3 is detected, the MAX20342 is configured according to *[Table 4](#page-21-0)*.

Accessory Mode Detection

The five accessory modes (Accessory 1-5) are detected by measuring the resistance on the SBU1 and SBU2 pins using the scheme detailed in the *[Resistive Measurement](#page-29-0)* section. The detection can be triggered manually (SBUDetManEn = 1), continuously (SBUDetContEn = 1), or one-shot (SBUDetOneShotEn = 1). One detection consists of measuring the resistances on SBU1/SBU2 to ground in sequence, reporting the results, and asserting the corresponding interrupts.

Manual trigger runs one detection as soon as SBUDetManEn is set to 1 (except in shutdown mode). Continuous and oneshot triggering work only when the device is in Debug Accessory Sink Mode (CCStat[2:0] = 0b111). With one-shot triggering, a single detection is run upon entering Debug Accessory Sink Mode. For continuous triggering, the detection is run periodically every 200ms until a resistance is found within one of the five accessory mode resistance ranges, or until the Debug Accessory Sink Mode is exited.

After both the SBU1 and SBU2 resistive measurements are completed, individual results are reported in the SBU1DetResult1/2 and SBU2DetResult1/2 registers, and the ResSBUInt interrupt is asserted. The overall result is derived based on these individual results and the SBUDetAbortPriority value as listed in *[Table 6](#page-29-1)*. The corresponding ResAbortInt, ResOpenInt, or ResGroundInt interrupt is also asserted respectively if the overall result is Abort, Open, or Ground. If the overall result is a Finite resistance but not in any of the five accessory mode resistance ranges, a ResFiniteInt is asserted. If it is within one of these ranges, the corresponding ResAcc1-5Int interrupt is asserted.

Figure 6. SBU1/SBU2 Resistance Detection

Table 6. SBU Detection Overall Result

Resistive Measurement

The resistive measurement circuitries used for both moisture detection and SBU1/SBU2 accessory mode detection are the same. As shown in *[Figure 7](#page-30-0)*, it consists of an 8-bit SAR ADC, four switchable pullup currents, one bank of pullup switches, and one bank of pulldown switches. Each USB Type-C pin has one pulldown switch and two pullup switches associated with it. The pulldown switch (each with RMOIST_SWPD on-resistance) connects the pin to ground, while the two pullup switches (each with RMOIST_SWPU on-resistance) connect the pin to the forced node where the pullup current source is connected and to the sensed node where the ADC is connected, respectively.

For example, to measure resistance between SBU1 and the other USB Type-C pins, the two pullup switches of SBU1 are closed, connecting SBU1 to the forced and sensed nodes. The pulldown switches of the other USB-C pins are also closed so that those pins are all grounded. When the pullup current is switched onto the forced node, the current flows through the resistance (between SBU1 and ground) and the voltage on SBU1 is sensed by the ADC on the sensed node. The resistance can then be determined, knowing the forced pullup current and the sensed voltage. These pullup and pulldown switches can be automatically or manually configured as described in the *[Moisture Detection](#page-23-1)* section. In accessory mode detection, only the pullup switches on SBU1 and SBU2 (alternately) are enabled.

Figure 7. Resistive Measurement Simplified Diagram

For each measurement, the ADC takes $N = 2_{ADC}$ mums $[2:0]$ samples and records the maximum, minimum, and average values among these samples. To avoid operating the ADC with a small input level where the offset error is dominant, the device starts with the 2µA pullup current and increases it by a factor of four when the average ADC reading is lower than nearly a quarter of the ADC full scale value (see *[Figure 8](#page-32-0)* for details), this continues until the maximum 128µA pullup current is reached. The final measurement result is reported in the ADCResultAvg/Min/Max[7:0] and IpuResult[1:0] register bits.

To address the intrinsic resistive measurement errors of the MAX20342, ADC shift factors are set and the device compares the ADC average reading to the threshold of (0x3F - ADC shift factor) when deciding whether or not to increase the pullup current by a factor of four. This helps prevent clamping the average ADC reading when the pullup current is increased prematurely due to the measurement errors (quantified by the RSBU_ACC and RCCCD_ACC parameters in the ECT).

The parameters ADCSBUCorrNum[4:0], RSBU_ACC, RSBU_RNG, and RSBU_RNG_GND apply when only the SBU1 and/or SBU2 pins are pulled up. In specific, these parameters always apply in accessory mode detection. For moisture detection, these parameters only apply in the following cases: during two of the four burst measurements (when SBU1 and SBU2 are pulled up), and when only SBU1 and/or SBU2 (not any other pins) are pulled up in Manual Configuration. In all the other moisture detection cases, the parameters ADCCorrNum[5:0], RCCCD_ACC, RCCCD_RNG, and RCCCD_RNG_GND apply.

Open/Ground/Abort/Finite Result

The flow of the resistive measurement is depicted in [Figure 8.](#page-32-0) There are four possible results for each measurement, namely Open, Ground, Abort, and Finite:

Open: If the resistance on the node is open, the final imposed pullup current should be 2μA, while ADCResultMax[7:0] and ADCResultAvg[7:0] clamp at 0xFF (assuming ADCNoiseClampRng[5:0] is set to 0x00, as it should be in most cases). The Open result is reported with $|pu$ Result $|1:0|$ = 00 and ADCResultAvg/Min/Max = 0xFF.

Ground: If the resistance on the node is ground, the final imposed pullup current should be 128µA and the average ADC reading should be lower or equal than ADCGroundVth[3:0]. The Ground result is reported with IpuResult[1:0] = 11 and ADCResultAvg/Min/Max = 0x00.

Abort: If the resistive measurement returns one of the two listed results, it retries for up to ADCRetryNum[3:0] times. If the same result is returned for ADCRetryNum[3:0] times, the Abort result is reported with IputResult[1:0] = 00 and ADCResultAvg/Min/Max = 0x00. Abort indicates that the device is unable to determine the resistance due to unfiltered noise or uncorrected measurement error on the node. It is not expected to occur in most applications.

- 1. (ADCResultMax[7:0] = 0xFF) AND (IputResult[1:0] = 2μA) AND (ADCResultAvg[7:0] < (0xFF ADCNoiseClampRng[5:0]))
- 2. (ADCResultMax[7:0] = 0xFF) AND (lputResult[1:0] = 8μ A, 32 μ A, or 128 μ A)

Finite: The Finite resistance is reported if one of the two listed conditions is met. ADC_shift factor is equal to ADCSBUCorrNum[4:0] when only SBU1 and/or SBU2 are pulled up and equal to ADCCorrNum[5:0] in other cases. The detected resistance can be calculated with the final imposed current reflected in IpuResult[1:0], the sensed voltage reflected in ADCResultAvg[7:0], and the LSB of the ADC: R = ADCResultAvg[7:0] x LSB / IpuResult[1:0].

- 1. (ADCResultAvg[7:0] > (0x3F ADC shift factor)) AND (ADCResultMax[7:0] < 0xFF)
- 2. (ADCResultAvg[7:0] ≤ (0x3F ADC shift factor)) AND (ADCResultAvg[7:0] > ADCGroundVth[3:0] AND IputResult[1:0] = 128μA)

Figure 8. Resistive Measurement Flow

Moisture Detection and Accessory Mode Detection Auto-Detectable Resistances and Voltage Thresholds Setting

The allowed ranges from which the user can pick the target resistance values to be automatically detected are shown in *[Table 7](#page-33-0)* and *[Table 8](#page-33-1)*.

To account for the resistance measurement errors ($R_{SBU,ACC}$ and $R_{CCCD,ACC}$), the moisture detection voltage threshold, RMoistDetVth[7:0], must be set with the corresponding accuracy percentage with the chosen pullup current. For the accessory mode detection, the minimum and maximum voltage thresholds, RAcc_DetVMin[7:0] and RAcc_DetVMax[7:0], for each of the five accessory modes also need to be adjusted with the corresponding accuracy percentage with the chosen pullup current. If the resistor on the SBU1 (or SBU2) has additional tolerance, error band RBAND needs to be widened by decreasing RAcc_DetVMin[7:0] and increasing RAcc_DetVMax[7:0] to account for the additional resistance variat

Table 7. Auto Detectable Resistance Ranges and Accuracies - Accessory Mode Detection and Moisture Detection When Only SBU1 and/or SBU2 Are Pulled Up

For example, to detect an accessory resistance value of 30kΩ, perform the following procedure:

- The target resistance is 30kΩ. Use *[Table 7](#page-33-0)* to find the resistance range and measurement accuracy in which 30kΩ falls into. In this example, the target resistance belongs to the 32μA pullup current range.
- Compute the typical voltage target: $30k\Omega \times 32\mu A = 0.96V$.
- Since only SBU pins are pulled up, RSBU_ACC applies, namely the combined accuracy of the ADC and the 32μA pullup current (see *[Table 7](#page-33-0)*). Compute the minimum and maximum accessory mode detection voltage thresholds with the measurement accuracy (4.75%).
- Minimum threshold: $0.96V \times (1 4.70\%) = 0.91488V$. With conversion, RAcc_DetVMin[7:0] = 155 = 0x9B.
- Maximum threshold: $0.96V \times (1 + 4.70\%) = 1.00512V$. With conversion, RAcc_DetVMax[7:0] = 171 = 0xAB.
- The calculation refers to an ideal external resistance with zero tolerance. In practice, decreasing the minimum and increasing the maximum voltage thresholds by an amount dictated by the actual tolerance is necessary.
- With an external resistor (1% tolerance), the minimum and maximum voltage thresholds would be:
- Minimum threshold: $0.91488V \times (1 1\%) = 0.90573V$. With conversion, RAcc_DetVMin[7:0] = 153 = 0x99.
- Maximum threshold: $1.00512V \times (1 + 1\%) = 1.01517V$. With conversion, RAcc_DetVMax[7:0] = 173 = 0xAD.

Table 8. Auto Detectable Resistance Ranges and Accuracies - Moisture Detection in Other Cases

For example, to detect a moisture resistance threshold of 20kΩ, perform the following procedure (the CC1 or CC2 pin is pulled up):

- The target resistance is 20kΩ. Use **[Table 8](#page-33-1)** to find the resistance range and measurement accuracy in which 20kΩ falls into. In this example, the target resistance belongs to the 32μA pullup current range.
- Compute the typical voltage target: $20k\Omega \times 32\mu A = 0.64V$.
- Since pin(s) different from SBU1 and/or SBU2 only (i.e., CC1 and CC2) are pulled up, RCCCD_ACC applies, namely the combined accuracy of the ADC and the 32μA pullup current (see **[Table 8](#page-33-1)**). Compute the minimum moisture detection voltage threshold with the measurement accuracy (5.44%).
- Moisture threshold: $0.64V \times (1 5.44\%) = 0.60518V$. With conversion, RMoistDetVth[7:0] = 102 = 0x66.
- The calculation refers to an ideal external resistance with zero tolerance. In practice, decreasing the moisture detection voltage threshold by an amount dictated by the actual tolerance is necessary.
- With an external resistor (1% tolerance), the moisture threshold would be $0.60518V \times (1 1\%) = 0.59913V$. With conversion, RMoistDetVth $[7:0] = 101 = 0 \times 65$.

Ground Threshold for Accessory Mode Detection and Moisture Detection

The actual resistance ground condition ranges, RSBU_RNG_GND and RCCCD_RNG_GND, are determined by setting ADCGroundVth[3:0] with the following formulas:

RSBU_RNG_GND = [5.823mV x (ADCGroundVth[3:0] – 1) – 4.35mV] / 131.059μA

RCCCD_RNG_GND = [5.823mV x (ADCGroundVth[3:0] – 1) – 4.35mV] / 131.600μA

For example, the default of ADCGroundVth[3:0] is 0b0100 or decimal 4. Therefore:

RSBU_RNG_GND = $[5.823mV x (4 – 1) – 4.35mV] / 131.059 \mu A = 100.11Ω (The ECT value)$

 $RCCCD_RNG_GND = [5.823mV x (4 – 1) – 4.35mV] / 131.600μA = 99.70Ω (The ECT value)$

V_B Overvoltage Protection

The device features overvoltage protection up to $+28V$ on the V_B line. If the input voltage exceeds the overvoltage lockout threshold (V_{B OVLO}), the low 50mΩ (typ) on-resistance internal FET disconnects V_B from OUT to protect low-voltage systems against voltage faults. The device features soft-start capability to minimize inrush current by slowly turning the internal FET on when the V_B voltage is valid for a period longer than the debounce time (t_{VBFLT} DEB). When an overvoltage event occurs, the fault flag or interrupt is asserted depending on the INTEn configuration in the COMM_CTRL1 register.

USB Data Switch (TDN/TDP)

The device supports Hi-Speed, full-speed, and low-speed USB signal levels. The USB channel is bidirectional and has low R_{ON} _{TD} 3.2Ω (typ) on-resistance and C_{ON} _{TD} 4.5pF (typ) on-capacitance. The low on-resistance is stable as the analog input signals are swept from ground to 5.5V for low signal distortion.

UART Switch (UT, UR)

The MAX20342 supports standard single-supply UART signals. The UART channel supports high-speed signals. The UART channel is bidirectional and has a R_{ON-U} 23 Ω (typ) on-resistance.

Fault State

The device enters the Fault state when there is either an overvoltage condition on BAT (V_{BAT_OVLO}) or a thermal condition (T_{DE} > T_{SHDN}). In either condition, the FAULT bit (bit 7 of register 0x07) becomes 1. After the device exits the overvoltage and thermal conditions, the FAULT bit remains asserted and the user needs to clear it by writing 1 to the FaultUnlock bit (bit 0 of register 0x19) to resume normal operation.

Thermal Shutdown

The MAX20342 features a thermal shutdown protection feature to protect the device from fault conditions. When the die temperature is T_{SHDN}, the device enters thermal shutdown mode and the fault flag or interrupt is asserted depending on the INTEn configuration in the COMM_CTRL1 register. When the die temperature drops below 150°C (typ), the user can write 1 to the FaultUnlock bit to clear the FAULT status bit and resume operation.

Supply Voltage Selector

The MAX20342 features an internal supply voltage selector that chooses between V_B and BAT inputs to power the internal blocks. If V_B is not present, the internal power supply, V_{CCINT} , is supplied from BAT. A typical 100µs POR is provided at the rising edge of $V_{\rm CC}$. When the device is connected to $V_{\rm B}$, the user can force the device to use BAT as the supply of V_{CC} through the COMM_CTRL1 register VCCINTOnBAT bit.

Low-Power Modes

To minimize power consumption, the MAX20342 supports three different low power modes: shutdown (ShdnMode), lowpower UFP (LPUFP), and low-power DRP (LPDRP). Shutdown is the lowest power consumption mode. LPUFP has the UFP emulation on. LPDRP has the DRP emulation on.

Shutdown

To minimize power consumption to the lowest possible level when inactive, the MAX20342 features a low-power shutdown mode that is activated through the register COMM_CTRL1 ShdnMode enable bit in the I²C interface. When ShdnMode = 1, the device enters low-power state, and the battery current is reduced to I_{BAT} SHDN. In this condition, the only blocks that are active are the I2C interface and the CC pin monitoring to detect the charger connection. All other blocks are disabled. On the I2C bus, the device exits shutdown mode when a logic-low is detected on either SDA or SCL for more than 50ns (typ).

Interrupts

The MAX20342 generates an interrupt for any bit status change in the I2C status register. The INTEn bit enables the interrupt output. When INTEn is disabled, all interrupts are masked but not cleared. The $\overline{\text{INT}}$ pin is defaulted as a flag function when the interrupt is disabled (INTEn = 0). In this condition, the \overline{INT} pin is pulled low when an invalid or an unknown charger is inserted or when a UART factory cable is detected.

I2C Interface

The MAX20342 contains an I_2C -compatible interface for data communication with a host controller (SCL and SDA). The interface supports a clock frequency of up to 1000kHz. SCL and SDA require pullup resistors that are connected to a positive supply.

Figure 9. I ²C Interface Timing

When writing to the MAX20342 using the I²C interface, the master sends a START condition (S) followed by the MAX20342 I²C address. After the address, the master sends the register address of the register that is to be programmed. The master then ends communication by issuing a STOP condition (P) to relinquish control of the bus, or a REPEATED START condition (Sr) to communicate to another I²C slave.

Figure 10. I ²C START, STOP, and REPEATED START Conditions

Slave Address

The MAX20342 slave address is 0b0110101 (0x35) plus the Read/Write bit. Set the Read/Write bit high to configure the MAX20342 to read mode (0x6B). Set the Read/Write bit low to configure the MAX20342 to write mode (0x6A).

Bit Transfer

One data bit is transferred on the rising edge of each SCL clock cycle. The data on SDA must remain stable during the high period of the SCL clock pulse. Changes in SDA while SCL is high and stable are considered control signals (see **[Figure 10](#page-36-0)**). Both SDA and SCL remain high when the bus is not active.

Single-Byte Write

In this operation, the master sends an address and two data bytes to the slave device. The following procedure describes the single byte write operation:

- 1. The master sends a START condition.
- 2. The master sends the 7-bit slave address plus a write bit (low).
- 3. The addressed slave asserts an ACK on the data line.
- 4. The master sends the 8-bit register address.
- 5. The slave asserts an ACK on the data line only if the address is valid (NAK if not).
- 6. The master sends 8 data bits.
- 7. The slave asserts an ACK on the data line.
- 8. The master generates a STOP condition.

Figure 11. Write Byte Sequence

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Burst Write

In this operation, the master sends an address and multiple data bytes to the slave device. The slave device automatically increments the register address after each data byte is sent, unless the register being accessed is 0x00, in which case the register address remains the same. The following procedure describes the burst write operation:

- 1. The master sends a START condition.
- 2. The master sends the 7-bit slave address plus a write bit (low).
- 3. The addressed slave asserts an ACK on the data line.
- 4. The master sends the 8-bit register address.
- 5. The slave asserts an ACK on the data line only if the address is valid (NAK if not).
- 6. The master sends 8 data bits.
- 7. The slave asserts an ACK on the data line.
- 8. Repeat step 6 and step 7 N-1 times.
- 9. The master generates a STOP condition.

Figure 12. Burst Write Sequence

Single Byte Read

In this operation, the master sends an address plus two data bytes and receives one data byte from the slave device. The following procedure describes the single byte read operation:

- 1. The master sends a START condition.
- 2. The master sends the 7-bit slave address plus a write bit (low).
- 3. The addressed slave asserts an ACK on the data line.
- 4. The master sends the 8-bit register address.
- 5. The slave asserts an ACK on the data line only if the address is valid (NAK if not).
- 6. The master sends a REPEATED START condition.
- 7. The master sends the 7-bit slave address plus a read bit (high).
- 8. The addressed slave asserts an ACK on the data line.
- 9. The slave sends 8 data bits.
- 10. The master asserts a NACK on the data line.
- 11. The master generates a STOP condition.

Figure 13. Read Byte Sequence

Burst Read

In this operation, the master sends an address plus two data bytes and receives multiple data bytes from the slave device. The following procedure describes the burst byte read operation:

- 1. The master sends a START condition.
- 2. The master sends the 7-bit slave address plus a write bit (low).
- 3. The addressed slave asserts an ACK on the data line.
- 4. The master sends the 8-bit register address.
- 5. The slave asserts an ACK on the data line only if the address is valid (NAK if not).
- 6. The master sends a REPEATED START condition.
- 7. The master sends the 7-bit slave address plus a read bit (high).
- 8. The slave asserts an ACK on the data line.
- 9. The slave sends 8 data bits.
- 10. The master asserts an ACK on the data line.
- 11. Repeat step 9 and step 10 N-2 times.
- 12. The slave sends the last 8 data bits.
- 13. The master asserts a NACK on the data line.
- 14. The master generates a STOP condition.

Figure 14. Burst Read Sequence

Acknowledge Bits

Data transfers are acknowledged with an acknowledge bit (ACK) or a not-acknowledge bit (NACK). Both the master and the MAX20342 generate ACK bits. To generate an ACK, pull SDA low before the rising edge of the ninth clock pulse and hold it low during the high period of the ninth clock pulse. To generate a NACK, leave SDA high before the rising edge of the ninth clock pulse and leave it high for the duration of the ninth clock pulse. Monitoring for NACK bits allows for detection of unsuccessful data transfers.

Figure 15. Acknowledge Bits

Register Map

MAX20342

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Register Details

REVISION_ID (0x00)

COMMON_INT (0x01)

CC_INT (0x02)

BC_INT (0x03)

OVP_INT (0x04)

RES_INT1 (0x05)

RES_INT2 (0x06)

COMMON_STATUS (0x07)

CC_STATUS1 (0x08)

CC_STATUS2 (0x09)

BC_STATUS (0x0A)

OVP_STATUS (0x0B)

COMMON_MASK (0x0C)

CC_MASK (0x0D)

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BC_MASK (0x0E)

OVP_MASK (0x0F)

RES_MASK1 (0x10)

RES_MASK2 (0x11)

COMM_CTRL1 (0x15)

COMM_CTRL2 (0x16)

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COMM_CTRL3 (0x19)

OVP_CTRL (0x1A)

CC_CTRL0 (0x20)

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CC_CTRL1 (0x21)

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CC_CTRL2 (0x22)

CC_CTRL3 (0x23)

CC_CTRL4 (0x24)

CC_CTRL5 (0x25)

CC_CTRL6 (0x26)

VCONN_ILIM (0x28)

BC_CTRL0 (0x2A)

BC_CTRL1 (0x2B)

SBU1DetResult1 (0x2C)

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SBU1DetResult2 (0x2D)

SBU2DetResult1 (0x2E)

SBU2DetResult2 (0x2F)

SBUDetCtrl (0x30)

RAcc1DetVMax (0x31)

RAcc1DetVMin (0x32)

RAcc1DetIpu (0x33)

RAcc2DetVMax (0x34)

RAcc2DetVMin (0x35)

RAcc2DetIpu (0x36)

RAcc3DetVMax (0x37)

RAcc3DetVMin (0x38)

RAcc3DetIpu (0x39)

RAcc4DetVMin (0x3A)

RAcc4DetVMax (0x3B)

RAcc4DetIpu (0x3C)

RAcc5DetVMax (0x3D)

RAcc5DetVMin (0x3E)

RAcc5DetIpu (0x3F)

RMoistDetVth (0x50)

MoistDetCtrl (0x51)

MoistDetPUConfig (0x52)

MoistDetPDConfig (0x53)

MoistDetAutoCC1Result1 (0x54)

MoistDetAutoCC1Result2 (0x55)

MoistDetAutoCC2Result1 (0x56)

MoistDetAutoCC2Result2 (0x57)

MoistDetAutoSBU1Result1 (0x58)

MoistDetAutoSBU1Result2 (0x59)

MoistDetAutoSBU2Result1 (0x5A)

MoistDetAutoSBU2Result2 (0x5B)

ADCCtrl1 (0x5C)

ADCCtrl2 (0x5D)

ADC_CTRL3 (0x5E)

ADC_CTRL4 (0x5F)

ADCResultAvg (0x60)

ADCResultMax (0x61)

ADCResultMin (0x62)

VB_CTRL (0x63)

Applications Information

Hi-Speed USB

Hi-Speed USB requires careful PCB layout with 45Ω single-ended/90Ω differential controlled-impedance traces that are matched by equal lengths.

Power Supply Bypassing

Bypass V_B , V_{DD} , and BAT with 1µF ceramic capacitors to GND as close as possible to the device.

Power-On Reset (POR)

The MAX20342 provides secure operation with the power-on reset circuits. When the power supply for the device exceeds the POR rising value 1.6V (typ) and stays above the maximum falling edge, the internal logic is in a known state for safe operation. However, the *[Electrical Characteristics](#page-3-0)* table parameters are not guaranteed until the V_B and BAT voltages meet the specified global conditions.

Choosing I2C Pullup Resistors

The I2C interface requires pullup resistors to provide a logic-high level to data and clock lines. There are trade-offs between power dissipation and speed, and a compromise must be made in choosing pullup resistor values. Every device connected to the bus introduces some capacitance even when the device is not in operation. The I2C interface specifies 120ns rise time to go from low to high (30% to 70%) for fast mode plus, which is defined for a clock frequency up to 1000kHz (see the I2C specifications in the *[Electrical Characteristics](#page-3-0)* table for details). To meet the rise time requirement, choose pullup resistors so that the rise time $t_R = 0.85 \times R_{PULLUP} \times C_{BUS} < 120$ ns. If the transition time becomes too slow, the setup and hold times might not be met and waveforms might not be recognized.

Resetting the I2C Bus from Suspend

If the I2C bus is suspended due to a weak or dead battery, an I2C STOP command needs to be performed after enabling the I2C buffers and pullup bias. The I2C STOP command is necessary before restarting the I2C traffic.

Extended ESD Protection

The CDP and CDN pins are protected against ESD up to $\pm 6kV$. The CC1, CC2, SBU1 and SBU2 pins are further protected up to ±15kV (HBM) without damage. The VB input withstands up to ±15kV (HBM) if bypassed with a 1µF ceramic capacitor close to the pin. The ESD structures withstand high ESD both in normal operation and when the device is powered down. After an ESD event, the MAX20342 continues to function without latch-up.

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model

[Figure 16](#page-89-0) shows the human-body model, while [Figure 17](#page-89-1) shows the current waveform it generates when discharged into a low-impedance state. This model consists of a 100pF capacitor charged to the ESD voltage of interest that is then discharged into the device through a 1.5kΩ resistor.

Figure 16. Human Body ESD Test Model

Figure 17. Human Body Current Waveform

IEC 61000-4-2

The IEC 61000-4-2 standard covers ESD testing and performance of finished equipment. It does not specifically refer to integrated circuits. The MAX20342 is specified for ±15kV Air-Gap and ±8kV Contact Discharge IEC 61000-4-2 on the CC1, CC2, SBU1, and SBU2 pins.

The main difference between tests done using the Human Body Model and IEC 61000-4-2 is higher peak current in IEC 61000-4-2. Because series resistance is lower in the IEC 61000-4-2 ESD test model (*[Figure 18](#page-90-0)*), the ESD-withstand voltage measured to this standard is generally lower than that measured using the HBM. *[Figure 19](#page-90-1)* shows the current waveform for the ±6kV IEC 61000-4-2 Level 4 ESD Contact Discharge test. The Contact Discharge method connects the probe to the device before the probe is energized.

Figure 18. IEC61000-4-2 ESD Test Model

Figure 19. IEC61000-4-2 ESD Generator Current Waveform

Typical Application Circuits

Ordering Information

+Denotes a lead(Pb)-free/RoHS-compliant package.

 $T =$ Tape and reel.